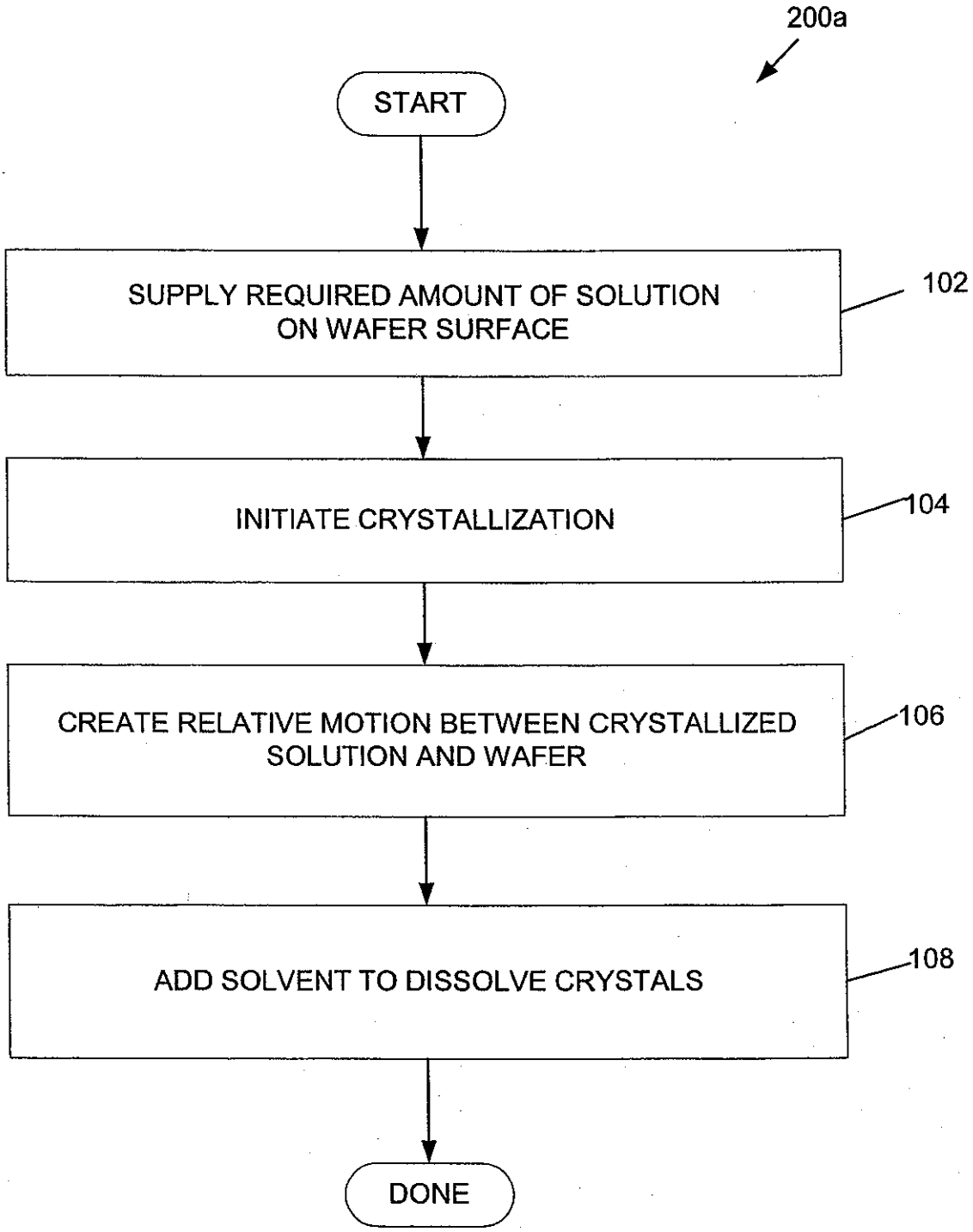

200a
START
SUPPLY REQUIRED AMOUNT OF SOLUTION ON WAFER SURFACE
102
INITIATE CRYSTALLIZATION
104
CREATE RELATIVE MOTION BETWEEN CRYSTALLIZED SOLUTION AND WAFER
106
ADD SOLVENT TO DISSOLVE CRYSTALS
108
DONE

FIG. 1

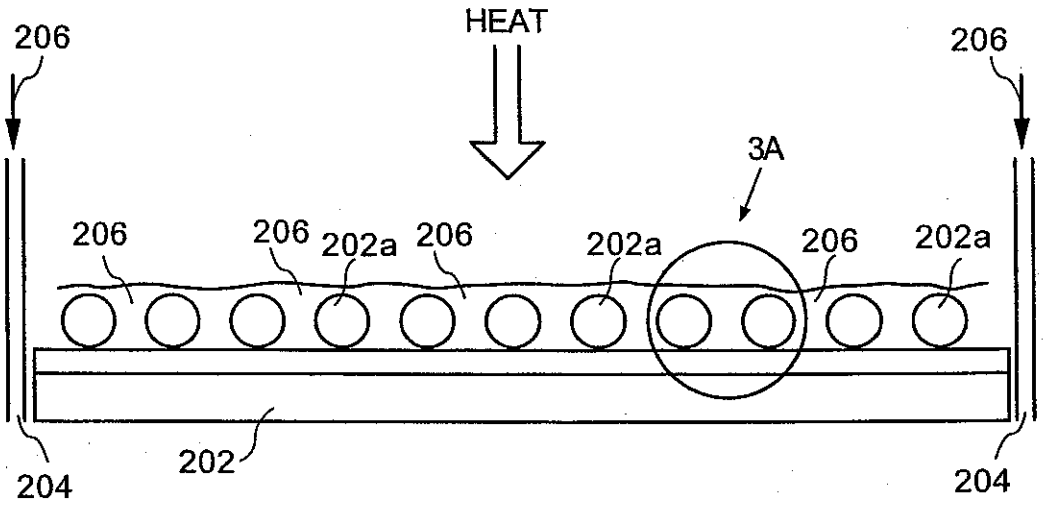


FIG. 2

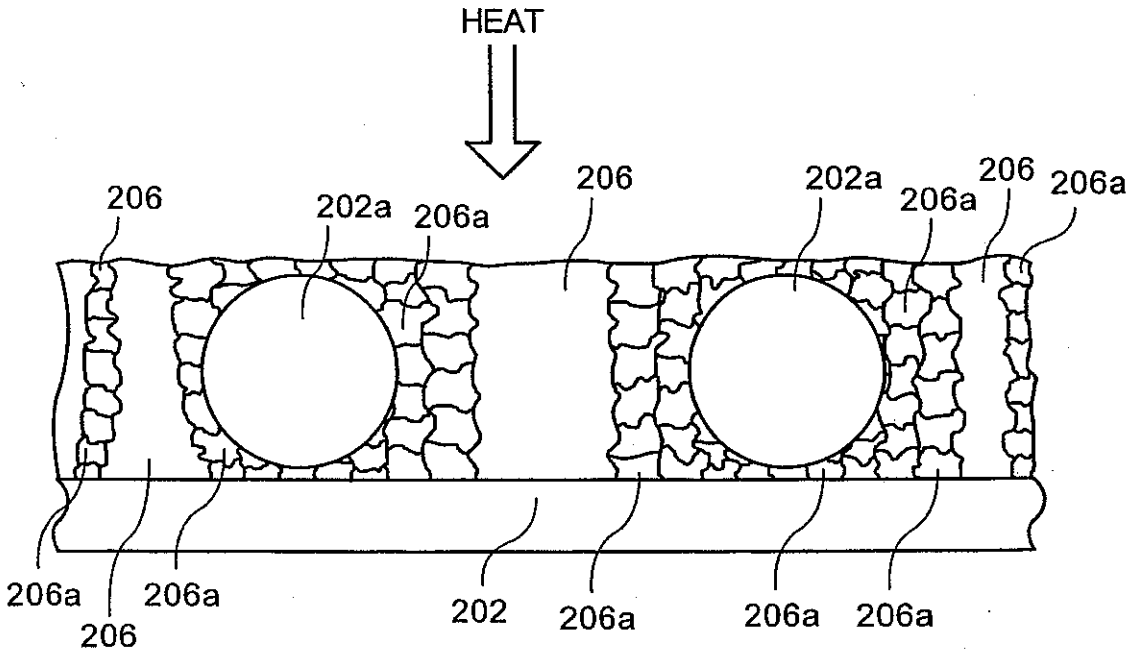

HEAT
206
202a
206a
206
202a
206a
206
206a
206a
206
206a
206
202
206a
206a
206a

FIG. 3A

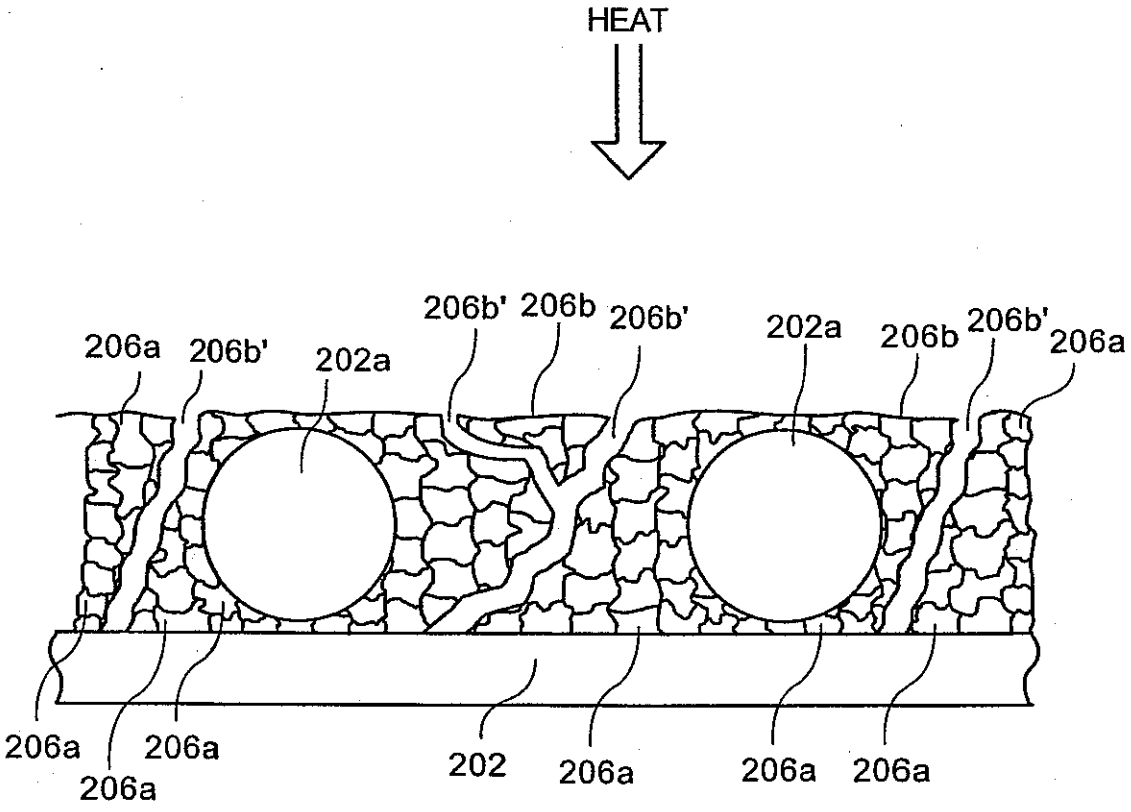

HEAT
206a
206b'
202a
206b'
206b
206b'
202a
206b
206b'
206a
206a
206a
206a
202
206a
206a
206a

FIG. 3B

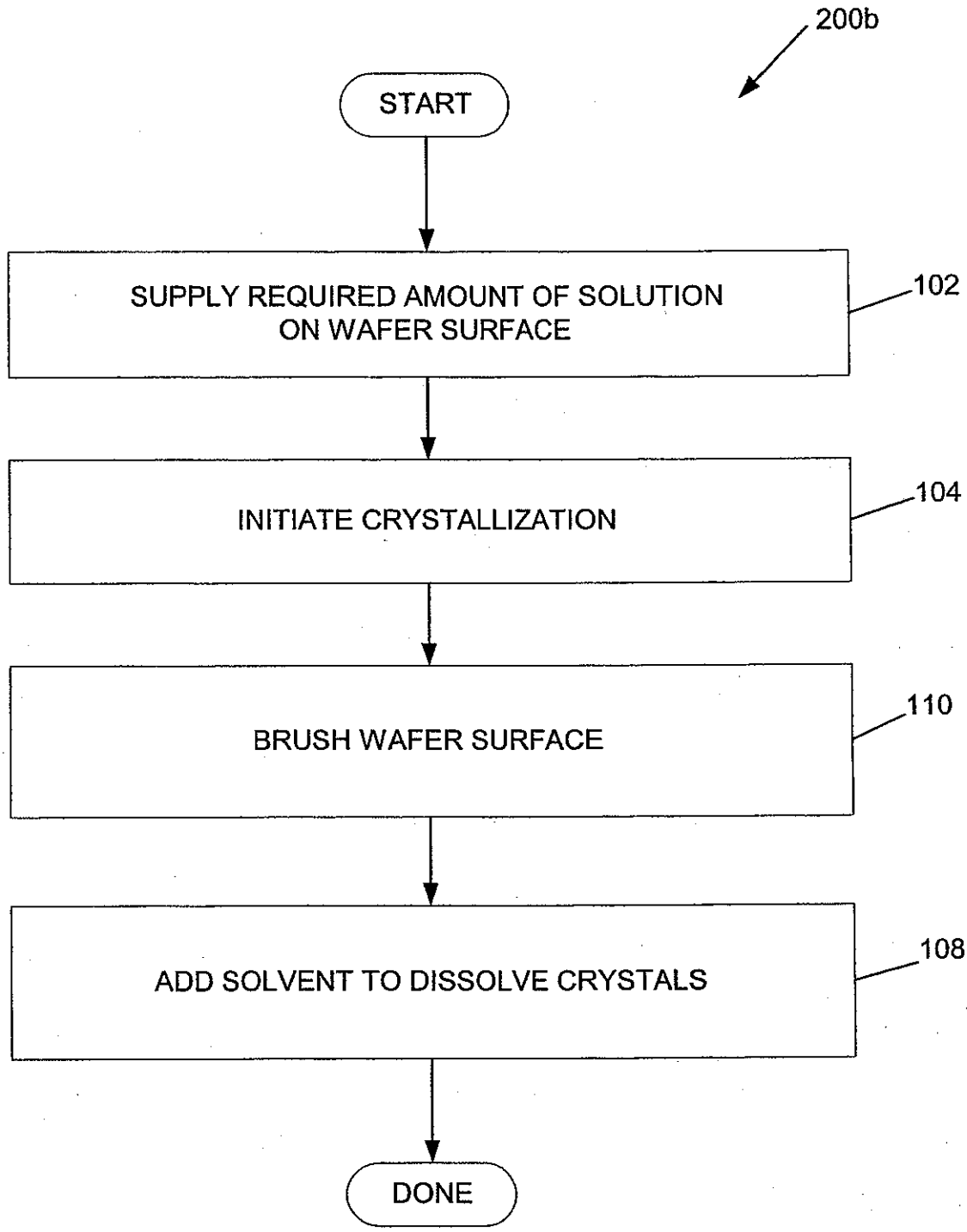

200b
START
SUPPLY REQUIRED AMOUNT OF SOLUTION ON WAFER SURFACE
102
INITIATE CRYSTALLIZATION
104
BRUSH WAFER SURFACE
110
ADD SOLVENT TO DISSOLVE CRYSTALS
108
DONE

FIG. 4

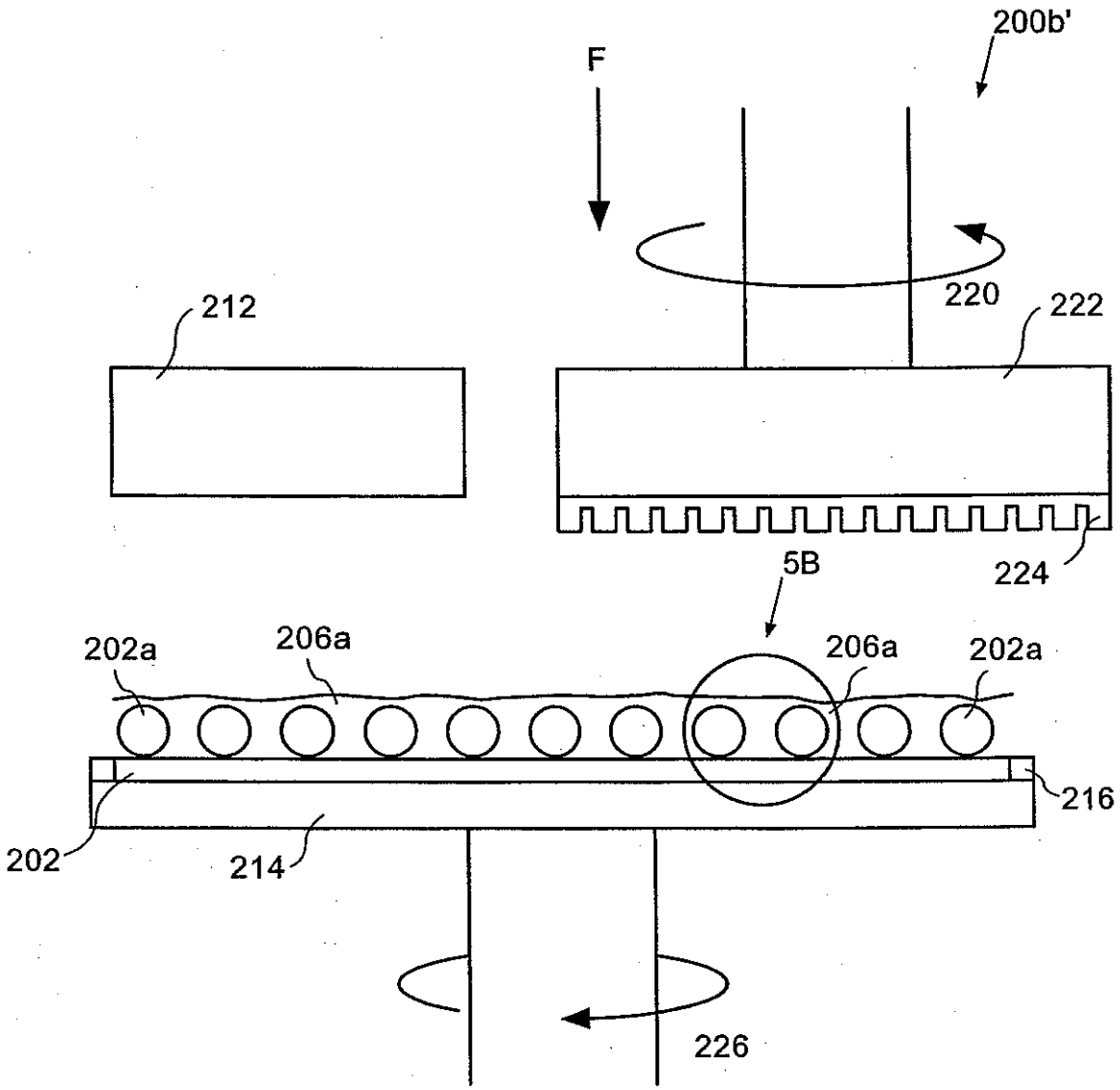

200b'
F
220
212
222
224
5B
202a
206a
206a
202a
216
202
214
226

FIG. 5A

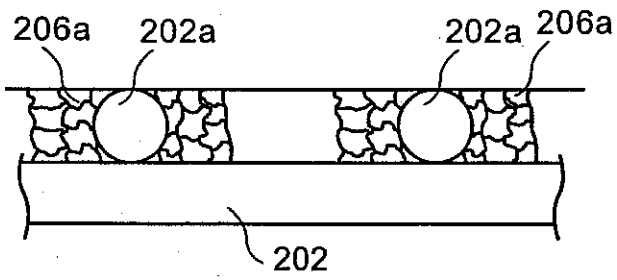

206a
202a
202a
206a
202

FIG. 5B

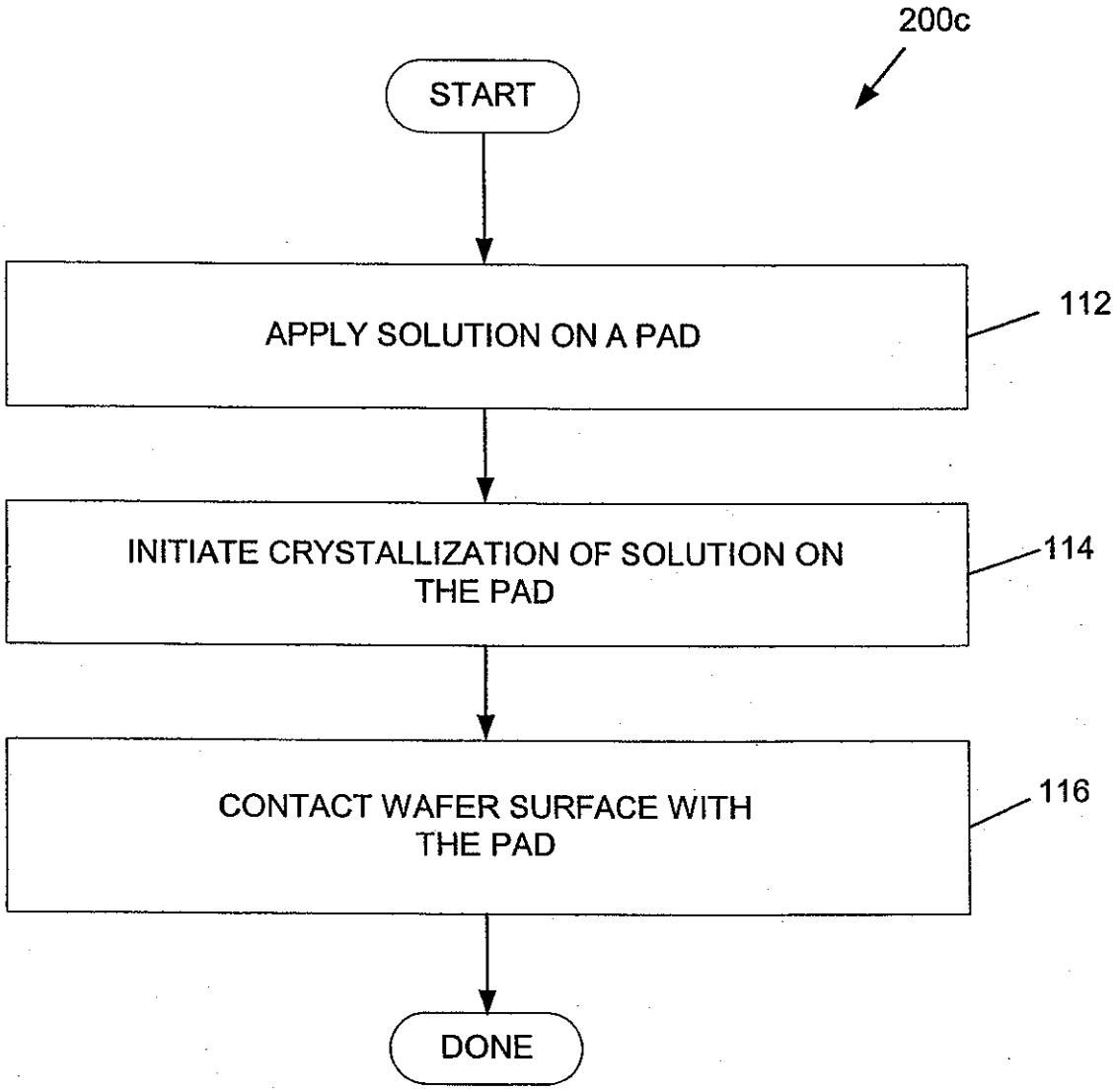

200c
START
APPLY SOLUTION ON A PAD
112
INITIATE CRYSTALLIZATION OF SOLUTION ON THE PAD
114
CONTACT WAFER SURFACE WITH THE PAD
116
DONE

FIG. 6

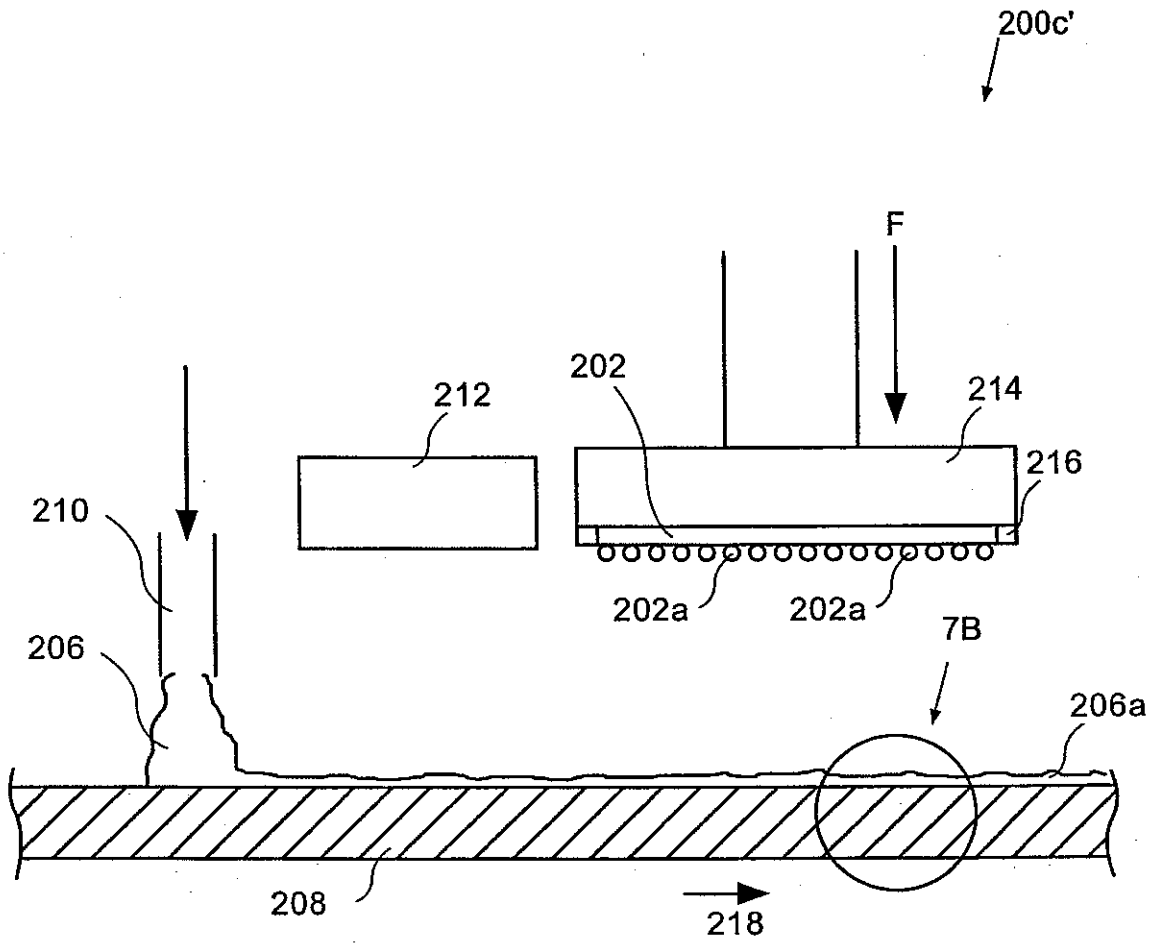

200c'
F
212
202
214
216
210
206
202a
202a
7B
206a
208
218

FIG.7A

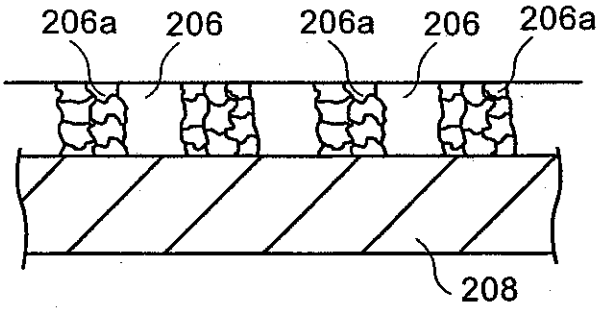

206a
206
206a
206
206a
208

FIG. 7B

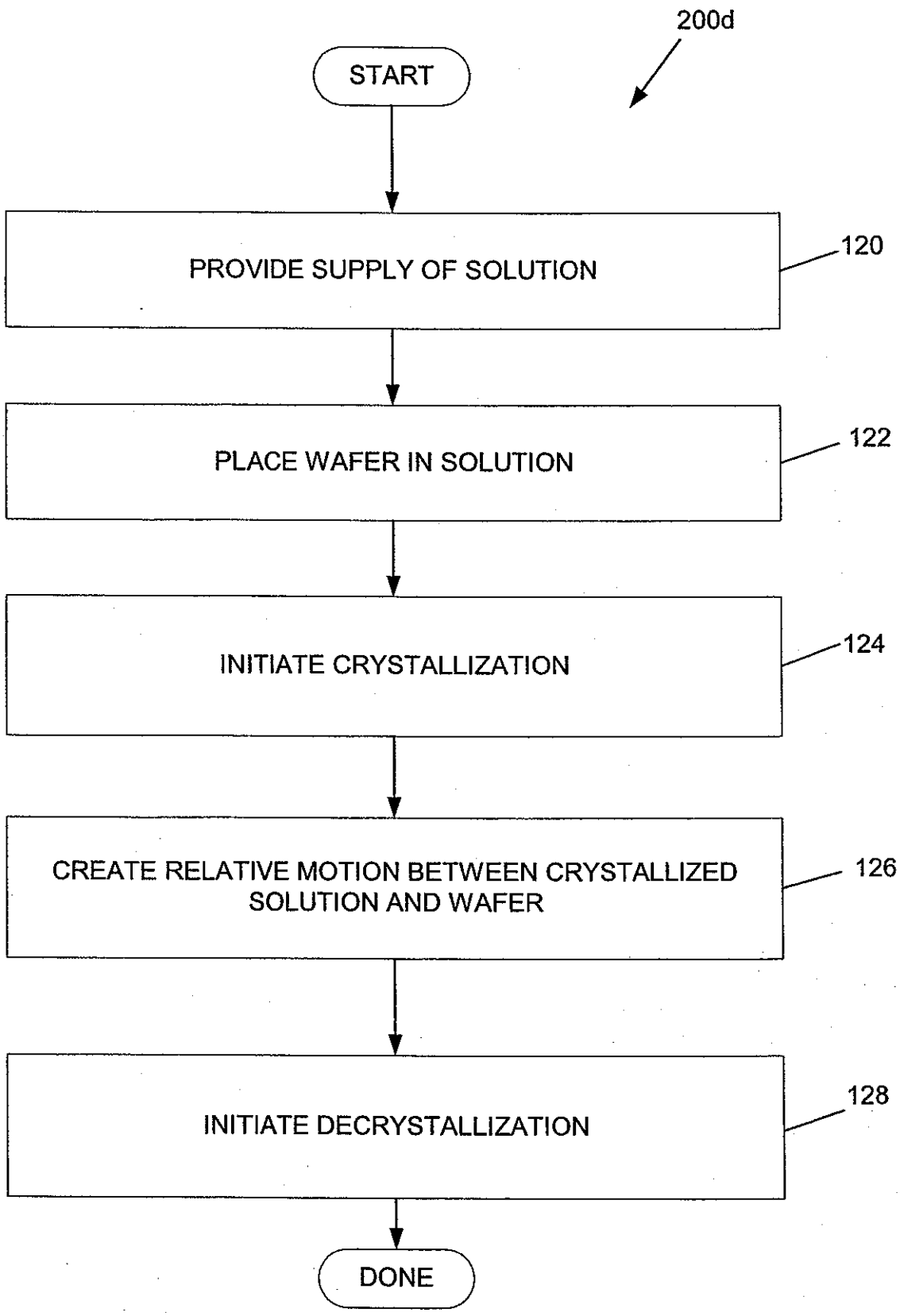

200d
START
PROVIDE SUPPLY OF SOLUTION
120
PLACE WAFER IN SOLUTION
122
INITIATE CRYSTALLIZATION
124
CREATE RELATIVE MOTION BETWEEN CRYSTALLIZED SOLUTION AND WAFER
126
INITIATE DECRYSTALLIZATION
128
DONE

FIG. 8